

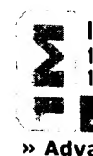
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L3	85	1 and (detect\$3 or determine)and(plurality or plural)and(leads\$1 or terminal\$1)and laterally near3 extent\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 15:42
L4	44	1 and (detect\$3 or determine)and(plurality or plural)and(leads\$1 or terminal\$1)and laterally near3 extent\$3 and coplanarity	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 15:43
L5	44	4 and (ccd or camera or sensor\$1 or detector\$1 or sens\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/09 15:46

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